IN THE CLAIMS:

This listing of clams will replace all prior versions, and listings, of claims in the application:

1-5. (canceled)

6. (currently amended) A method of manufacturing a self-light-emitting device, comprising the steps of:

filling a nozzle with an application liquid comprising an organic light-emitting material for forming an EL layer; and

continuously discharging said application liquid comprising said organic light-emitting material to a pixel column by ultrasonic oscillations while the nozzle and the pixel column are connected through the application liquid comprising said organic light-emittng material.

7. (original) A method of manufacturing a self-light-emitting device according to claim 6, wherein:

said nozzle has a large internal diameter portion and a small internal diameter portion;

said small internal diameter portion has a heater; and

said heater applies heat to the application liquid filling the nozzle.

8-9. (canceled)

10. (previously presented) A method of manufacturing a self-light-emitting device

according to claim 6, wherein said application liquid is pushed out from said nozzle by pressurization, and is applied.

11. (previously presented) A method of manufacturing a self-light-emitting device according to claim 6, wherein said application liquid is pushed out from said nozzle by a medium selected from a group consisting of capillary action, a weight of said application liquid and a pressure, and is applied.

12. (currently amended) A method of manufacturing a self-light-emitting device according to claim 19, wherein said application liquid filling said nozzle is applied by ~~contacting~~ bringing a contact element of said nozzle into contact with said bank.

13. (Withdrawn) A method of manufacturing a self-light-emitting device, comprising the steps of:

forming particles of an application liquid in a nozzle by applying an ultrasonic oscillation to the application liquid;

applying electric voltage to the particles for forming charged particles;

applying electric voltage to the charged particles for accelerating the charged particles;

applying electric voltage to the accelerated charged particles for controlling a flow of the accelerated charged particles.

14. (Withdrawn) A method of manufacturing a self-light-emitting device, comprising the steps of:

forming particles of an application liquid in a nozzle by applying an ultrasonic oscillation and heat to the application liquid;

applying electric voltage to the particles for forming charged particles;

applying electric voltage to the charged particles for accelerating the charged particles;

applying electric voltage to the accelerated charged particles for controlling a flow of the accelerated charged particles.

15. (Withdrawn) A method of manufacturing a self-light-emitting device according to claim 13, wherein the application liquid comprises at least a highly conductive solvent.

16. (Withdrawn) A method of manufacturing a self-light-emitting device according to claim 14, wherein the application liquid comprises at least a highly conductive solvent.

17. (Withdrawn) A method of manufacturing a self-light-emitting device according to claim 13, wherein the highly conductive solvent is toluene or N-methylpiloridon.

18. (Withdrawn) A method of manufacturing a self-light-emitting device according to claim 14, wherein the highly conductive solvent is toluene or N-methylpiloridon.

19. (previously presented) A method of manufacturing a light-emitting device according to claim 6, wherein said self-light-emitting device comprises a pixel electrode over a substrate and a bank covering at least an edge portion of said pixel electrode over said substrate.

20. (currently amended) A method of manufacturing a light-emitting device comprising:

filling a nozzle with an application liquid comprising an organic light-emitting material for forming an EL layer; and

continuously discharging said application liquid comprising said organic light-emitting material to a pixel column by ultrasonic oscillations and heat while the nozzle and the pixel column are connected through the application liquid comprising said organic light-emittng material.

21. (previously presnted) A method of manufacturing a light-emitting device according to claim 20, wherein said nozzle has a large internal diameter portion and a small internal diameter portion, said small internal diameter portion has a heater, and said heater applies heat to the application liquid filling the nozzle.

22. (previously presented) A method of manufacturing a light-emitting device according to claim 20, wherein said application liquid is pushed out from said nozzle by pressurization, and is applied.

23. (previously presented) A method of manufacturing a light-emitting device according to claim 20, wherein said application liquid is pushed out from said nozzle by a medium selected from

a group consisting of capillary action, a weight of said application liquid, and a pressure, and is applied.

24. (previously presented) A method of manufacturing a light-emitting device according to claim 20, wherein said light-emitting device comprises a pixel electrode over a substrate and a bank covering at least an edge portion of said pixel electrode over said substrate.

25. (currently amended) A method of manufacturing a light-emitting device according to claim 24, wherein said application liquid filling said nozzle is applied by ~~contacting~~ bringing a contact element of said nozzle into contact with said bank.

26. (currently amended) A method of manufacturing a light-emitting device comprising:

forming a thin film transistor over a substrate;

forming an insulating film over said thin film transistor;

forming a pixel electrode over said insulating film;

forming a bank covering at least an edge portion of said pixel electrode over said insulating film;

filling a nozzle with an application liquid comprising an organic light-emitting material for forming an EL layer; and

continuously discharging said application liquid comprising said organic light-emitting material to a pixel column by ultrasonic oscillations while the nozzle and the pixel column are connected through the application liquid comprising said organic light-emittng material.

27. (previously presented) A method of manufacturing a light-emitting device according to claim 26, wherein said nozzle has a large internal diameter portion and a small internal diameter portion, said small internal diameter portion has a heater, and said heater applies heat to the application liquid filling the nozzle.

28. (previously presented) A method of manufacturing a light-emitting device according to claim 26, wherein said application liquid is pushed out from said nozzle by pressurization, and is applied.

29. (previously presented) A method of manufacturing a light-emitting device according to claim 26, wherein said application liquid is pushed out from said nozzle by a medium selected from a group consisting of capillary action, a weight of said application liquid, and a pressure, and is applied.

30. (currently amended) A method of manufacturing a light-emitting device according to claim 26, wherein said application liquid filling said nozzle is applied by ~~contacting~~ bringing a contact element of said nozzle into contact with said bank.

31. (currently amended) A method of manufacturing a self-light-emitting device, comprising the steps of:

filling a nozzle with an application liquid comprising an organic light-emitting material for

forming an EL layer; and

continuously discharging said application liquid comprising said organic light-emitting material to a pixel column by ultrasonic oscillations with scanning the nozzle along a direction parallel to the pixel column while the nozzle and the pixel column are connected through the application liquid comprising said organic light-emittng material.

32. (previously presented) A method of manufacturing a self-light-emitting device according to claim 31, wherein:

said nozzle has a large internal diameter portion and a small internal diameter portion;

said small internal diameter portion has a heater; and

said heater applies heat to the application liquid filling the nozzle.

33. (previously presented) A method of manufacturing a self-light-emitting device according to claim 31, wherein said application liquid is pushed out from said nozzle by pressurization, and is applied.

34. (previously presented) A method of manufacturing a self-light-emitting device according to claim 31, wherein said application liquid is pushed out from said nozzle by a medium selected from a group consisting of capillary action, a weight of said application liquid and a pressure, and is applied.

35. (currently amended) A method of manufacturing a self-light-emitting device according

to claim ~~31~~ 36, wherein said application liquid filling said nozzle is applied by ~~contacting~~ bringing a contact element of said nozzle into contact with said bank.

36. (previously presented) A method of manufacturing a light-emitting device according to claim 31, wherein said self-light-emitting device comprises a pixel electrode over a substrate and a bank covering at least an edge portion of said pixel electrode over said substrate.

37. (currently amended) A method of manufacturing a light-emitting device comprising:

filling a nozzle with an application liquid comprising an organic light-emitting material for forming an EL layer; and

continuously discharging said application liquid comprising said organic light-emitting material to a pixel column by ultrasonic oscillations and heat with scanning the nozzle along a direction parallel to the pixel column while the nozzle and the pixel column are connected through the application liquid comprising said organic light-emittng material.

38. (previously presented) A method of manufacturing a light-emitting device according to claim 37, wherein said nozzle has a large internal diameter portion and a small internal diameter portion, said small internal diameter portion has a heater, and said heater applies heat to the application liquid filling the nozzle.

39. (previously presented) A method of manufacturing a light-emitting device according to claim 37, wherein said application liquid is pushed out from said nozzle by pressurization, and is

applied.

40. (previously presented) A method of manufacturing a light-emitting device according to claim 37, wherein said application liquid is pushed out from said nozzle by a medium selected from a group consisting of capillary action, a weight of said application liquid, and a pressure, and is applied.

41. (previously presented) A method of manufacturing a light-emitting device according to claim 37, wherein said light-emitting device comprises a pixel electrode over a substrate and a bank covering at least an edge portion of said pixel electrode over said substrate.

42. (currently amended) A method of manufacturing a light-emitting device according to claim ~~37~~ 41, wherein said application liquid filling said nozzle is applied by ~~contacting~~ bringing a contact element of said nozzle into contact with said bank.

43. (currently amended) A method of manufacturing a light-emitting device comprising:

forming a thin film transistor over a substrate;

forming an insulating film over said thin film transistor;

forming a pixel electrode over said insulating film;

forming a bank covering at least an edge portion of said pixel electrode over said insulating film;

filling a nozzle with an application liquid comprising an organic light-emitting material for

forming an EL layer; and

continuously discharging said application liquid comprising said organic light-emitting material to a pixel column by ultrasonic oscillations with scanning the nozzle along a direction parallel to the pixel column while the nozzle and the pixel column are connected through the application liquid comprising said organic light-emittng material.

44. (previously presented) A method of manufacturing a light-emitting device according to claim 43, wherein said nozzle has a large internal diameter portion and a small internal diameter portion, said small internal diameter portion has a heater, and said heater applies heat to the application liquid filling the nozzle.

45. (previously presented) A method of manufacturing a light-emitting device according to claim 43, wherein said application liquid is pushed out from said nozzle by pressurization, and is applied.

46. (previously presented) A method of manufacturing a light-emitting device according to claim 43, wherein said application liquid is pushed out from said nozzle by a medium selected from a group consisting of capillary action, a weight of said application liquid, and a pressure, and is applied.

47. (previously presented) A method of manufacturing a light-emitting device according to claim 43, wherein said application liquid filling said nozzle is applied by contacting a contact

element of said nozzle with said bank.